

FIG. 2B

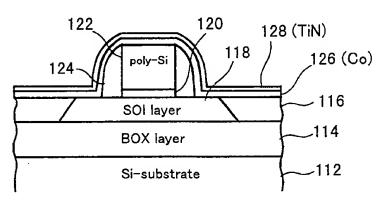
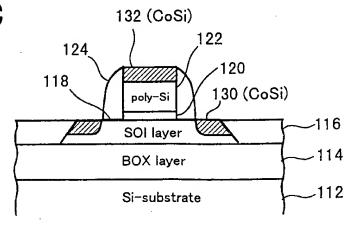
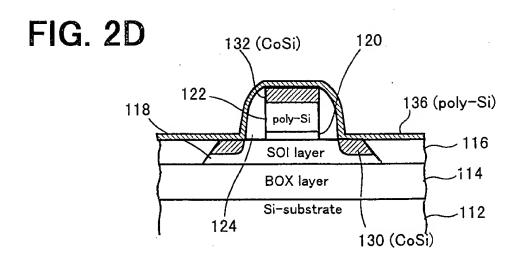




FIG. 2C







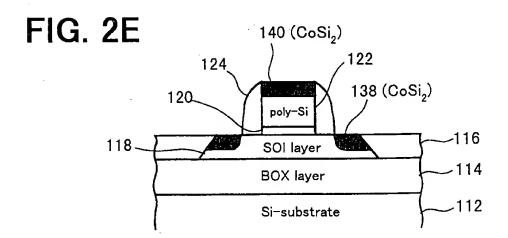
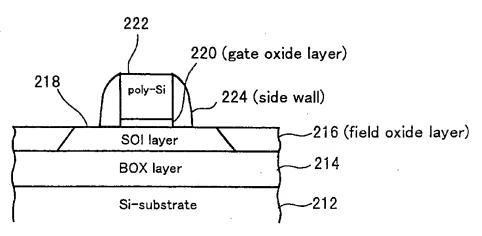


FIG. 3A



Sputtering (TiN, Co)

FIG. 3B

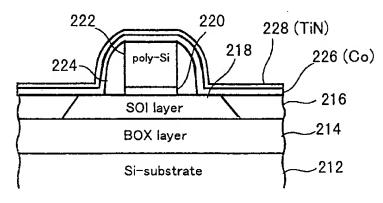
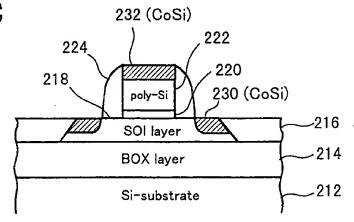
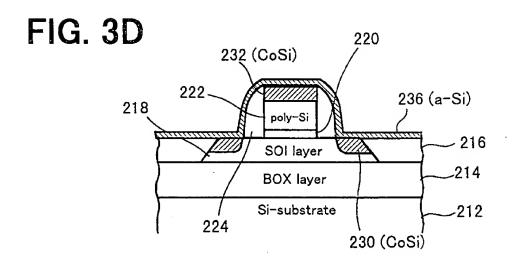




FIG. 3C







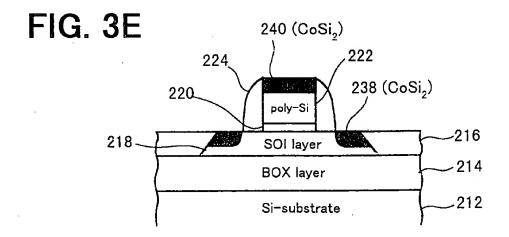
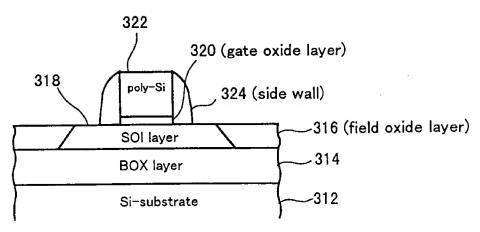
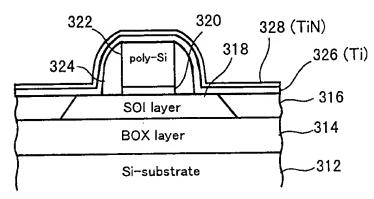


FIG. 4A



Sputtering (TiN, Co)

FIG. 4B



1st RTA

FIG. 4C

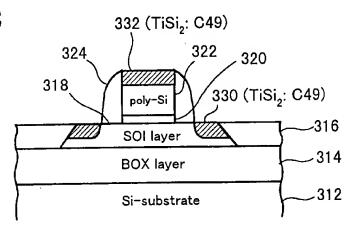
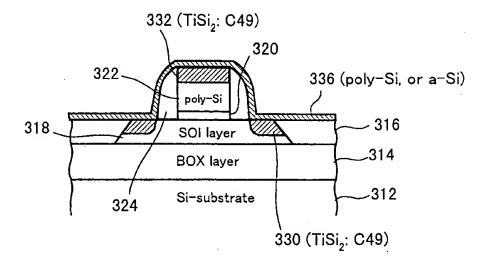


FIG. 4D





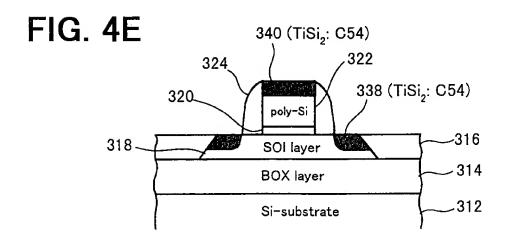


FIG. 5A

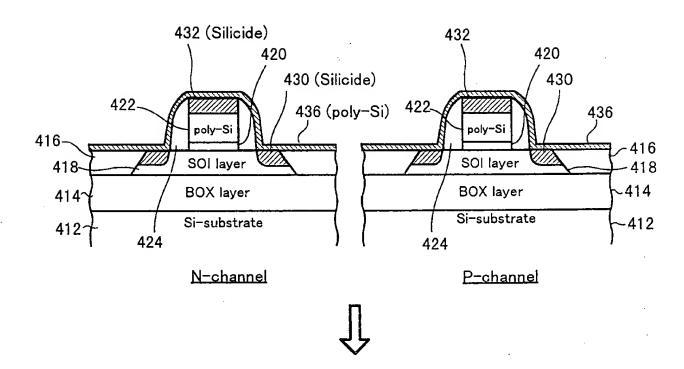
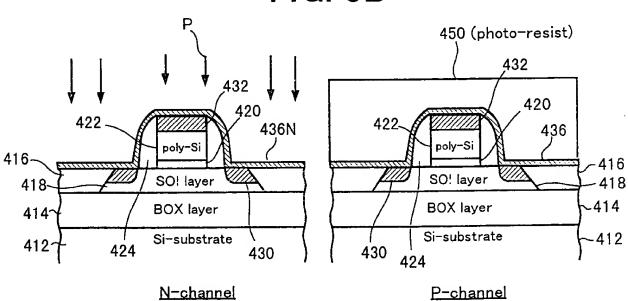


FIG. 5B



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FIG. 5C

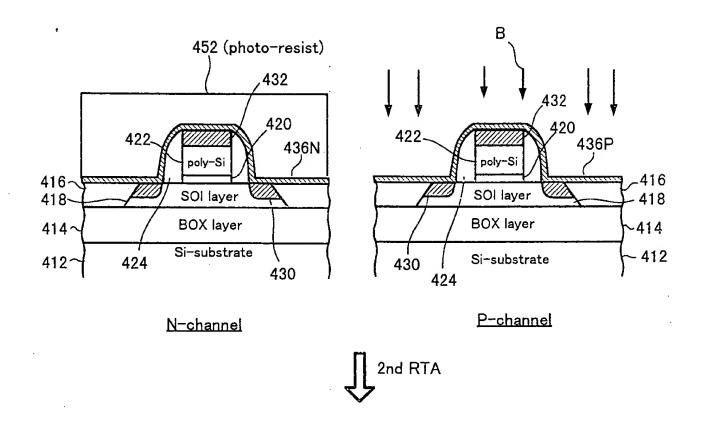
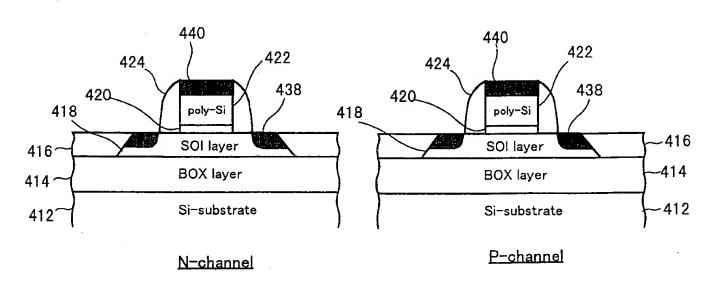


FIG. 5D





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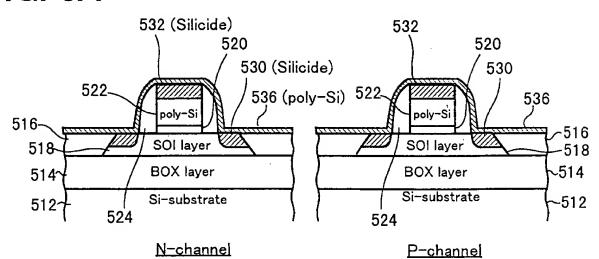


FIG. 6B 550 (photo-resist) 532 532 520 520 522 536N 522 536 516-516 SOI layer SOI layer 518 -518 **BOX** layer **-514 BOX** layer 5147 Si-substrate Si-substrate -512 512 524 530 530 524

